



## Material Content Data Sheet



<b>Sales Product Name</b>		BGB 741L7ESD E6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000509506						
<b>Package</b>		PG-TSLP-7-1		<b>Weight*</b>		1.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.11		1089	
	noble metal	gold	7440-57-5	0.007	0.42		4223	
	inorganic material	silicon	7440-21-3	0.049	3.13	3.66	31292	36604
leadframe	non noble metal	nickel	7440-02-0	0.329	20.81	20.81	208121	208121
wire	noble metal	gold	7440-57-5	0.051	3.20	3.20	32031	32031
encapsulation	organic material	carbon black	1333-86-4	0.011	0.68		6832	
	plastics	epoxy resin	-	0.146	9.22		92231	
	inorganic material	silicondioxide	60676-86-0	0.923	58.43	68.33	584129	683192
leadfinish	noble metal	gold	7440-57-5	0.032	2.00	2.00	20026	20026
plating	noble metal	gold	7440-57-5	0.032	2.00	2.00	20026	20026
*deviation	< 10%		Sum in total:			100,00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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